

### N-channel SiC power MOSFET

$V_{DSS}$	650V
R <sub>DS(on)</sub> (Typ.)	30m $Ω$
I <sub>D</sub>	70A
$P_D$	262W

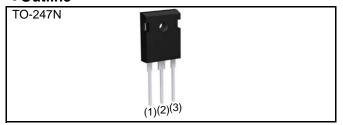
### Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating; RoHS compliant

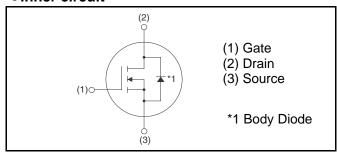
### Application

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating
- Motor drives

#### Outline



### •Inner circuit



### Packaging specifications

	Packing	Tube
	Reel size (mm)	-
Type	Tape width (mm)	-
Туре	Basic ordering unit (pcs)	30
	Taping code	C11
Marking		SCT3030AL

## ●Absolute maximum ratings (T<sub>a</sub> = 25°C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	$V_{ extsf{DSS}}$	650	V	
0	$T_c = 25^{\circ}C$	I <sub>D</sub> *1	70	А
Continuous drain current	$T_c = 100$ °C	I <sub>D</sub> *1	49	А
Pulsed drain current		I <sub>D,pulse</sub> *2	175	А
Gate - Source voltage		$V_{GSS}$	-4 to 22	V
Gate-Source Surge Voltage		$V_{GSS\_surge}$	-4 to 22	V
Recommended Drive Voltage		$V_{GS\_op}$	0 / 18	V
Junction temperature		T <sub>j</sub>	175	°C
Range of storage temperature		$T_{stg}$	-55 to +175	°C

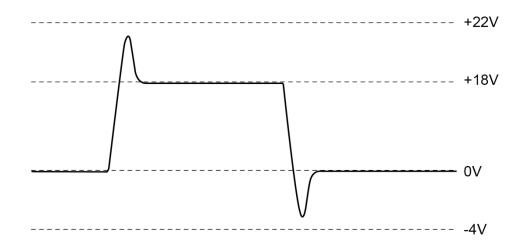
### ●Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Тур.	Max.	
Thermal resistance, junction - case	$R_{thJC}$	-	0.44	0.57	°C/W

### ●Electrical characteristics (T<sub>a</sub> = 25°C)

Doromotor	Symbol	Conditions	Values			Linit
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$ , $I_D = 1mA$	650	-	-	V
		$V_{DS} = 650 V, V_{GS} = 0 V$				
Zero gate voltage drain current	I <sub>DSS</sub>	T <sub>j</sub> = 25°C	-	1	10	μΑ
didiri odironi		T <sub>j</sub> = 150°C	-	2	-	
Gate - Source leakage current	I <sub>GSS+</sub>	$V_{GS} = +22V, V_{DS} = 0V$	-	-	100	nA
Gate - Source leakage current	I <sub>GSS</sub> _	$V_{GS} = -4V$ , $V_{DS} = 0V$	-	-	-100	nA
Gate threshold voltage	V <sub>GS (th)</sub>	$V_{DS} = 10V, I_{D} = 13.3 \text{mA}$	2.7	-	5.6	V
		$V_{GS} = 18V, I_D = 27A$				
Static drain - source on - state resistance	R <sub>DS(on)</sub> *3	T <sub>j</sub> = 25°C	-	30	39	mΩ
		T <sub>j</sub> = 125°C	-	39.6	-	
Gate input resistance	$R_{G}$	f = 1MHz, open drain	-	7	-	Ω

### ●Example of acceptable Vgs waveform



## ●Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol Conditions -		Values			Unit
raiailietei	Symbol Conditions	Min.	Тур.	Max.	Onit	
Transconductance	<b>g</b> fs *3	$V_{DS} = 10V, I_D = 27A$	-	9.4	-	S
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	1526	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 500V	-	89	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	42	-	
Effective output capacitance, energy related	C <sub>o(er)</sub>	$V_{GS} = 0V$ $V_{DS} = 0V$ to 300V	-	230	-	pF
Turn - on delay time	t <sub>d(on)</sub> *3	$V_{DD} = 300V, I_D = 18A$	-	22	-	
Rise time	t <sub>r</sub> *3	$V_{GS} = 18V/0V$	-	41	-	no
Turn - off delay time	t <sub>d(off)</sub> *3	$R_L = 17\Omega$	-	48	ı	ns
Fall time	t <sub>f</sub> *3	$R_G = 0\Omega$	-	27	-	
Turn - on switching loss	E <sub>on</sub> *3	$V_{DD} = 300V, I_{D} = 27A$ $V_{GS} = 18V/0V$	-	168	-	1
Turn - off switching loss	E <sub>off</sub> *3	$R_G = 0\Omega L = 250 \mu H$ * $E_{on}$ includes diode reverse recovery	-	112	-	μJ

## •Gate Charge characteristics $(T_a = 25^{\circ}C)$

Parameter	Symbol Condition	Conditions	Values			Unit
		Conditions	Min.	Тур.	Max.	Offic
Total gate charge	$Q_g^{*3}$	V <sub>DD</sub> = 300V	-	104	-	
Gate - Source charge	$Q_{gs}^{*3}$	I <sub>D</sub> = 27A	-	25	-	nC
Gate - Drain charge	Q <sub>gd</sub> *3	V <sub>GS</sub> = 18V	-	42	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} = 300V, I_D = 27A$	-	9.6	-	V

<sup>\*1</sup> Limited only by maximum temperature allowed.

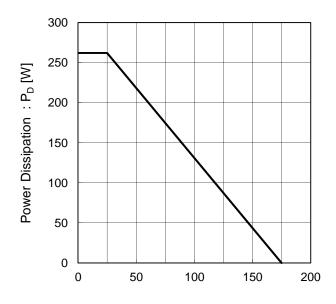
<sup>\*2</sup> PW  $\leq$  10  $\mu s,$  Duty cycle  $\leq$  1%

<sup>\*3</sup> Pulsed

## ullet Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

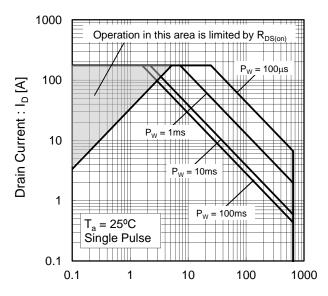
Parameter	Cumbal	Conditions	Values			Unit
	Symbol	Conditions	Min.	Тур.	Max.	Offic
Inverse diode continuous, forward current	l <sub>S</sub> *1	-T <sub>c</sub> = 25°C	-	1	70	А
Inverse diode direct current, pulsed	I <sub>SM</sub> *2		-	-	175	Α
Forward voltage	V <sub>SD</sub> *3	$V_{GS} = 0V, I_{S} = 27A$	-	3.2	ı	V
Reverse recovery time	t <sub>rr</sub> *3	I <sub>F</sub> = 27A, V <sub>R</sub> = 600V di/dt = 1100A/μs	-	26	1	ns
Reverse recovery charge	Q <sub>rr</sub> *3		-	130		nC
Peak reverse recovery current	I <sub>rrm</sub> *3		-	10	-	Α

Fig.1 Power Dissipation Derating Curve



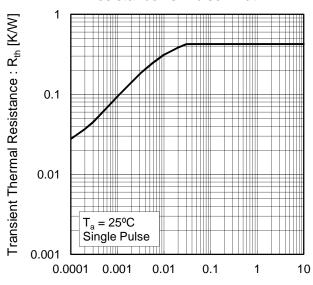
Junction Temperature : T<sub>i</sub> [°C]

Fig.2 Maximum Safe Operating Area



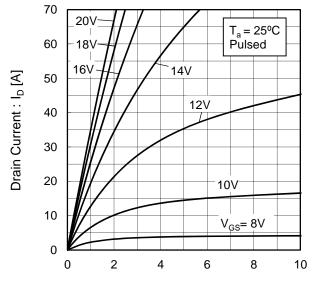
Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Typical Transient Thermal Resistance vs. Pulse Width



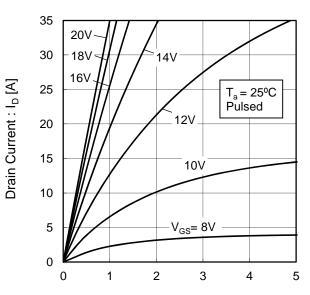
Pulse Width: Pw [s]

Fig.4 Typical Output Characteristics(I)

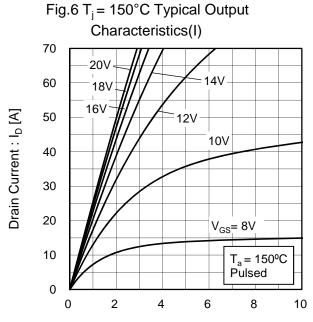


Drain - Source Voltage : V<sub>DS</sub> [V]

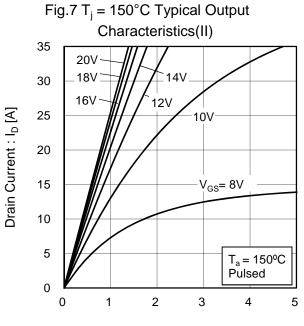
Fig.5 Typical Output Characteristics(II)



Drain - Source Voltage : V<sub>DS</sub> [V]

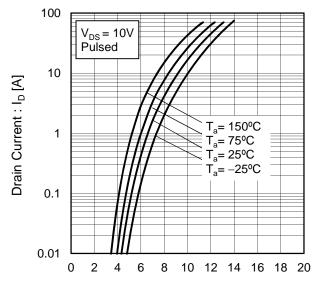


Drain - Source Voltage : V<sub>DS</sub> [V]



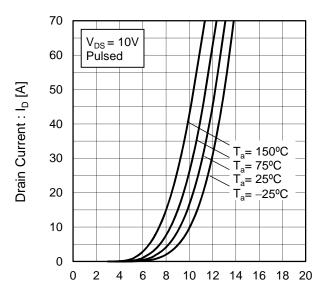
Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.8 Typical Transfer Characteristics (I)



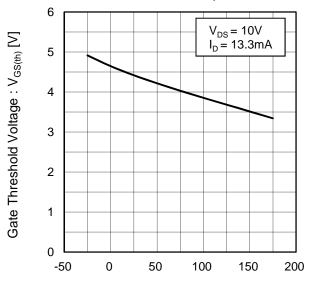
Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.9 Typical Transfer Characteristics (II)



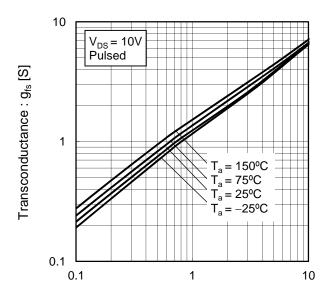
Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature



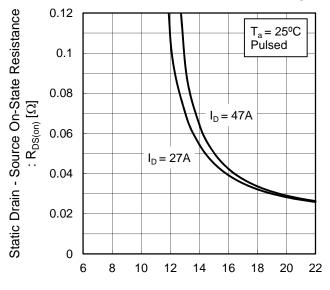
Junction Temperature :  $T_i$  [°C]

Fig.11 Transconductance vs. Drain Current



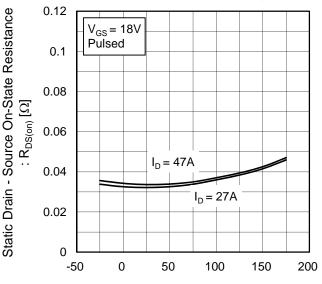
Drain Current : I<sub>D</sub> [A]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



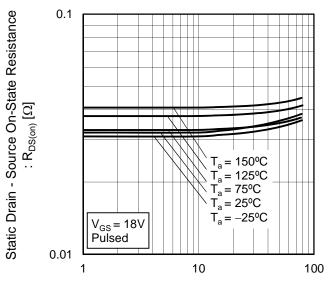
Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



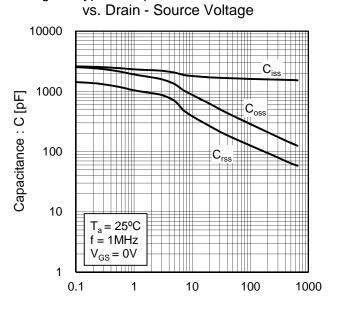
Junction Temperature : T<sub>i</sub> [°C]

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current



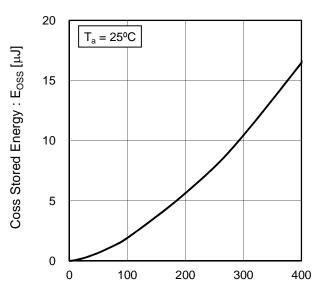
Drain Current :  $I_D$  [A]

Fig.15 Typical Capacitance



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.16 Coss Stored Energy



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.17 Switching Characteristics

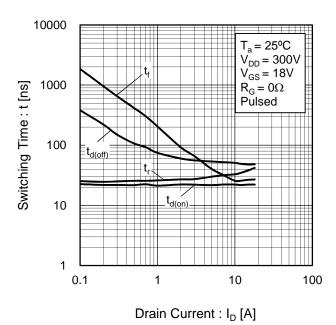
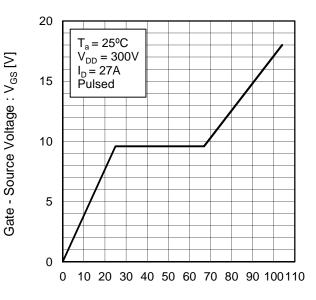
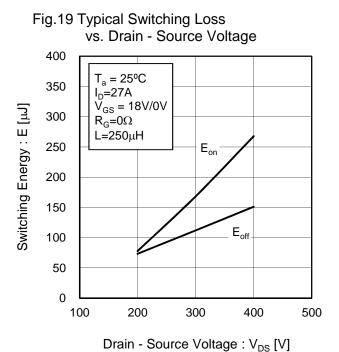


Fig.18 Dynamic Input Characteristics



Total Gate Charge : Q<sub>q</sub> [nC]



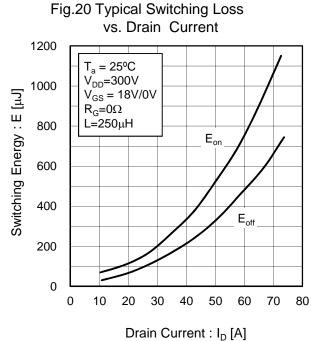
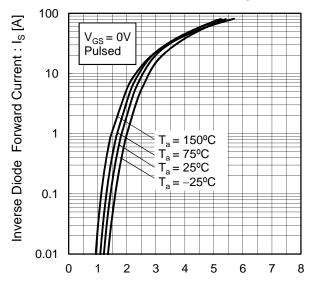


Fig.21 Typical Switching Loss vs. External Gate Resistance 1200  $T_a = 25^{\circ}C$ 1000  $V_{DD}^{"}=300V$  $I_D = 27A$  $\bar{V}_{GS} = 18V/0V$ 800 L=250μH  $\mathsf{E}_{\mathsf{on}}$ 600 400 200 0

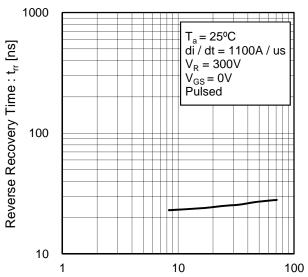
External Gate Resistance :  $R_G[\Omega]$ 

Fig.22 Inverse Diode Forward Current vs. Source - Drain Voltage



Source - Drain Voltage :  $V_{SD}$  [V]

Fig.23 Reverse Recovery Time vs.Inverse Diode Forward Current



Inverse Diode Forward Current: I<sub>S</sub> [A]

### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

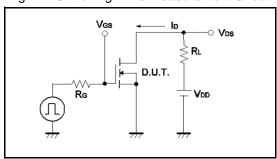


Fig.2-1 Gate Charge Measurement Circuit

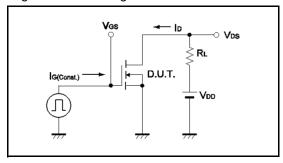


Fig.3-1 Switching Energy Measurement Circuit

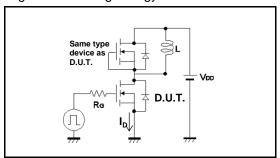


Fig.4-1 Reverse Recovery Time Measurement Circuit Fig.4-2 Reverse Recovery Waveform

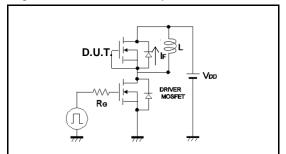


Fig.1-2 Switching Waveforms

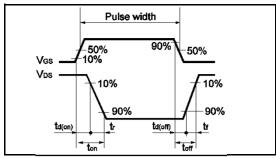


Fig.2-2 Gate Charge Waveform

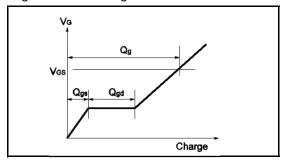
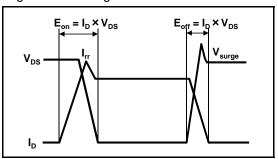
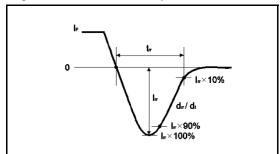


Fig.3-2 Switching Waveforms





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# SCT3030AL - Web Page

Part Number	SCT3030AL
Package	TO-247N
Unit Quantity	450
Minimum Package Quantity	30
Packing Type	Tube
Constitution Materials List	inquiry
RoHS	Yes